

# Back-contact solar cells at Fraunhofer ISE

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# Major advantages and challenges for IBC

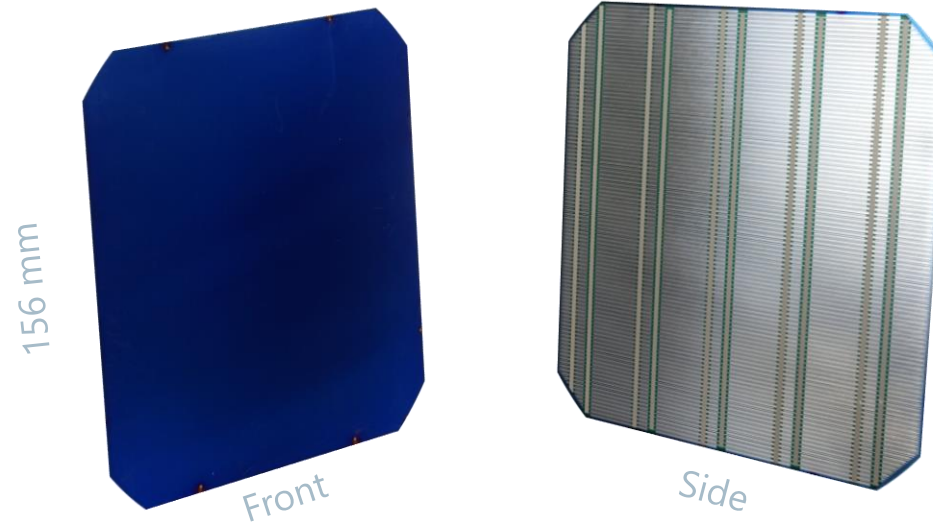
## Back-contacted solar cells

### Advantages of IBC solar cells

- Improved front side light absorption
- Very appealing aesthetics
- One sided interconnection, tighter spacing
- Soft breakdown in reverse bias
- ...

### Challenges for IBC mass manufacturing

- More complex processing, increased number of process steps
- Higher accuracy in manufacturing necessary
- Adjusted interconnection and module integration
- ...

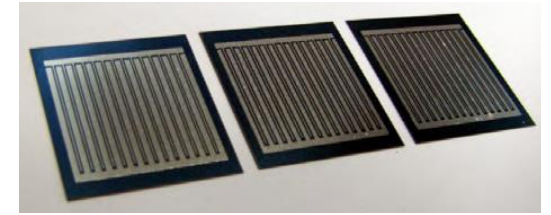


# Back-Contact Back-Junction Silicon Solar Cells

## Development at Fraunhofer ISE

- Fraunhofer ISE picked up BCBJ 25 years ago
- Development of homojunction silicon solar cells
  - Diffused junctions
  - Metallization by PVD
  - Structuring by photolithography
  - More than 50 process steps involved ...

		Area (cm <sup>2</sup> )	$j_{sc}$ (mA/cm <sup>2</sup> )	$V_{oc}$ (mV)	$FF$ (%)	$\eta$ (%)
1997	Glunz <i>et al.</i>	1	40.1	688	77.8	21.4
2002	Dicker <i>et al.</i>	1	39.8	698	79.4	22.1
2008	Granek <i>et al.</i>	4	38.8	665	82.5	21.3
2010	Reichel <i>et al.</i>	4	41.0	706	78.5	22.7
2012	Reichel <i>et al.</i>	4	41.2	697	80.0	23.0



### Preparation (9 steps)

Wafer cleaning, texturing, ...

### Junction Formation (28 steps)

Cleaning, Diffusion, Structuring, ...

### Surface Passivation (9 steps)

Cleaning , Front- and Rear  
passivation

### Metallization (12 steps)

Contact opening, evaporation and  
separation

3 Photolithography  
3 Diffusion processes

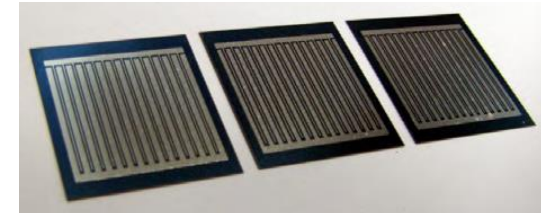
2 Photolithography

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~~3 Photolithography~~  
~~3 Diffusion processes~~

**1 Pre-deposition**  
**1 Co-Diffusion**

~~2 Photolithography~~  
**1 Screen printing**

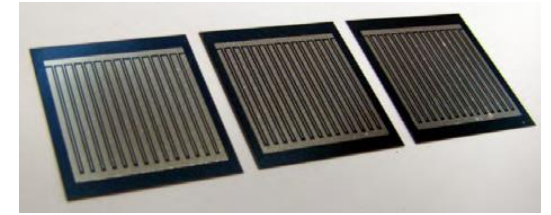
# Back-Contact Back-Junction Silicon Solar Cells

## Leanest process option

Our approach to minimize production effort

- Utilize one-sided inline processes for wet chemistry\*
  - Texturing, front side etch-back
- Implement Co-Diffusion with screen-printed BSG
  - Co-Diffusion with  $\text{POCl}_3$  (2-in-1, 3-in-1)
  - 3-in-1: Profile optimized for front side etch-back
- Use high quality surface passivation
  - ALD  $\text{Al}_2\text{O}_3$  / PECVD  $\text{SiN}_x$  stack for rear side
- Realize metallization with single screen printing step
  - Suitable metallization and pattern for interconnection

\* Not demonstrated, realized with masked batch processes



### Preparation (9 steps)

Wafer cleaning, texturing, ...

### Junction Formation (28 steps)

Cleaning, Diffusion, Structuring, ...

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Cleaning, Front- and Rear passivation

### Metallization (12 steps)

Contact opening, evaporation and separation

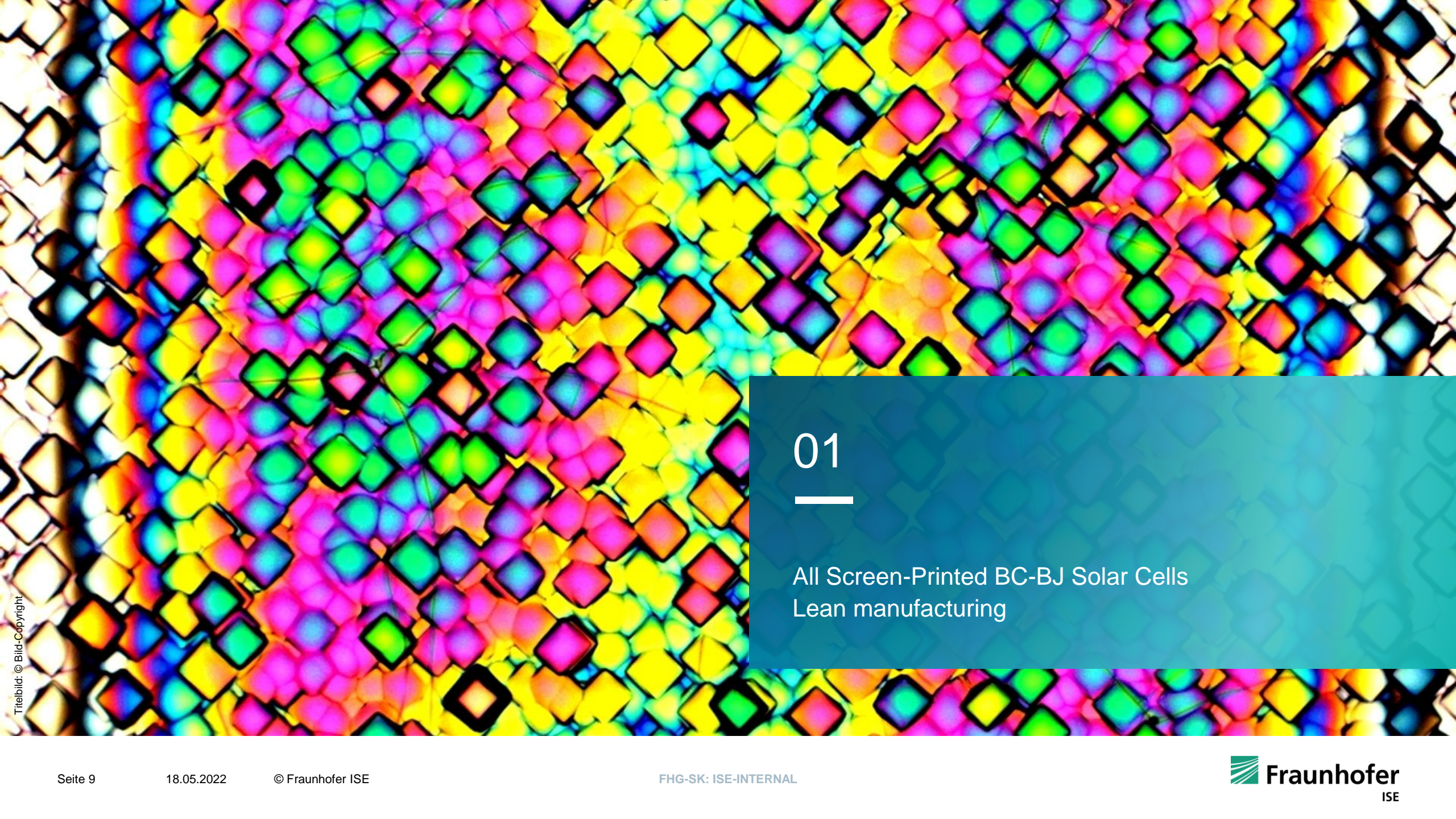
### Preparation (3 steps)

### Junction Formation (4 steps)

### Surface Passivation (5 steps)

### Metallization (2 steps)





01

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All Screen-Printed BC-BJ Solar Cells  
Lean manufacturing



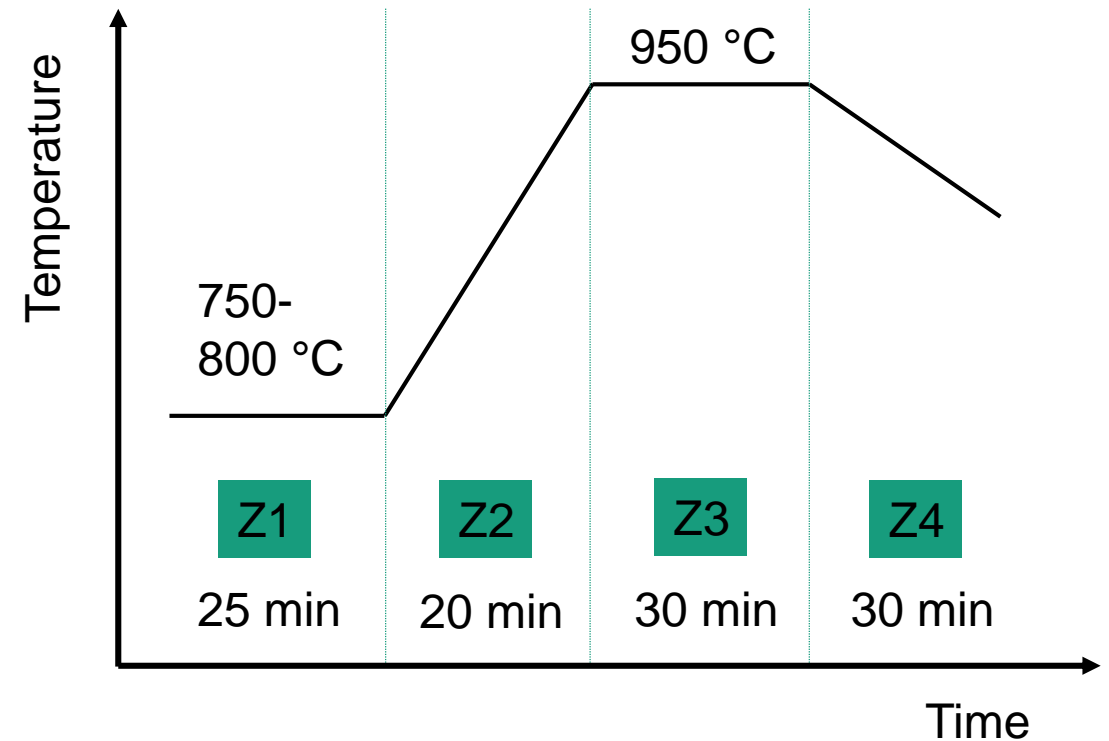
# Back-Contact Back-Junction Silicon Solar Cells

## Leanest process option

### Co-diffusion setup

- Pre-deposition of (suitable) dopant sources
  - PVD, PECVD, APCVD, Functional materials (printing), ...
  - Structuring if necessary
- Additional pre-deposition *in-situ* as an option
  - e.g. using  $\text{POCl}_3$  at medium elevated temperatures (750 °C – 800 °C)
- Drive-in of dopants at elevated temperature
  - e.g. at 950 °C for proper boron doping
- Challenges
  - Higher doping of P than B
  - Interference of B and P sources
  - Stability of sources
  - ...

### Schematic of Co-Diffusion

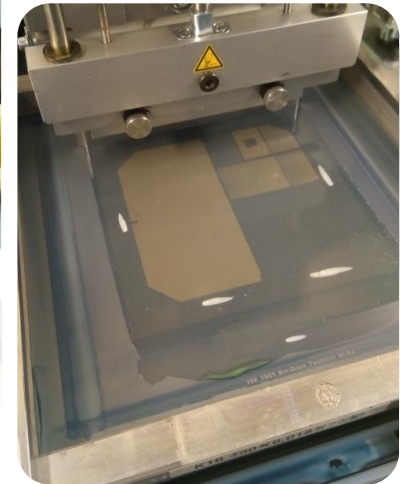
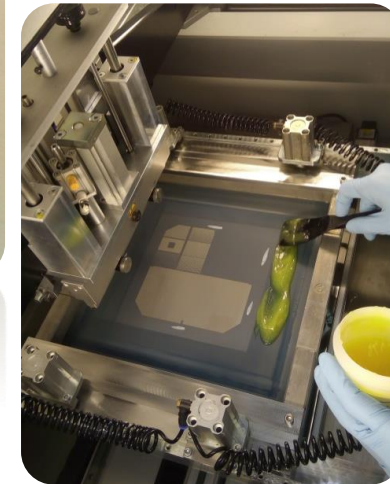


# Back-Contact Back-Junction Silicon Solar Cells

## Leanest process option

### Sol-Gel based BSG-paste

- Adjusted synthesis process aiming at screen printing
- Drying / Solidification after printing at medium temperatures
- Achieved feature sizes
  - Positive:  $89 \mu\text{m} \pm 5 \mu\text{m}$
  - Negative:  $71 \mu\text{m} \pm 4 \mu\text{m}$
- Much smaller than necessary for BCBJ
- Diffusion of up to  $1.8 \times 10^{20} \text{ cm}^{-3}$  at wafer surface (950 °C, 30 min)
  - Sheet resistance down to  $35 \Omega/\square$
- Blocking of  $\text{POCl}_3$  doping
- Cleaning with HF or adjusted etching
  - Surface passivation down to  $62 \text{ fA/cm}^2$  ( $46 \Omega/\square$ , ALD  $\text{Al}_2\text{O}_3$ )
- Also compatible with laser doping



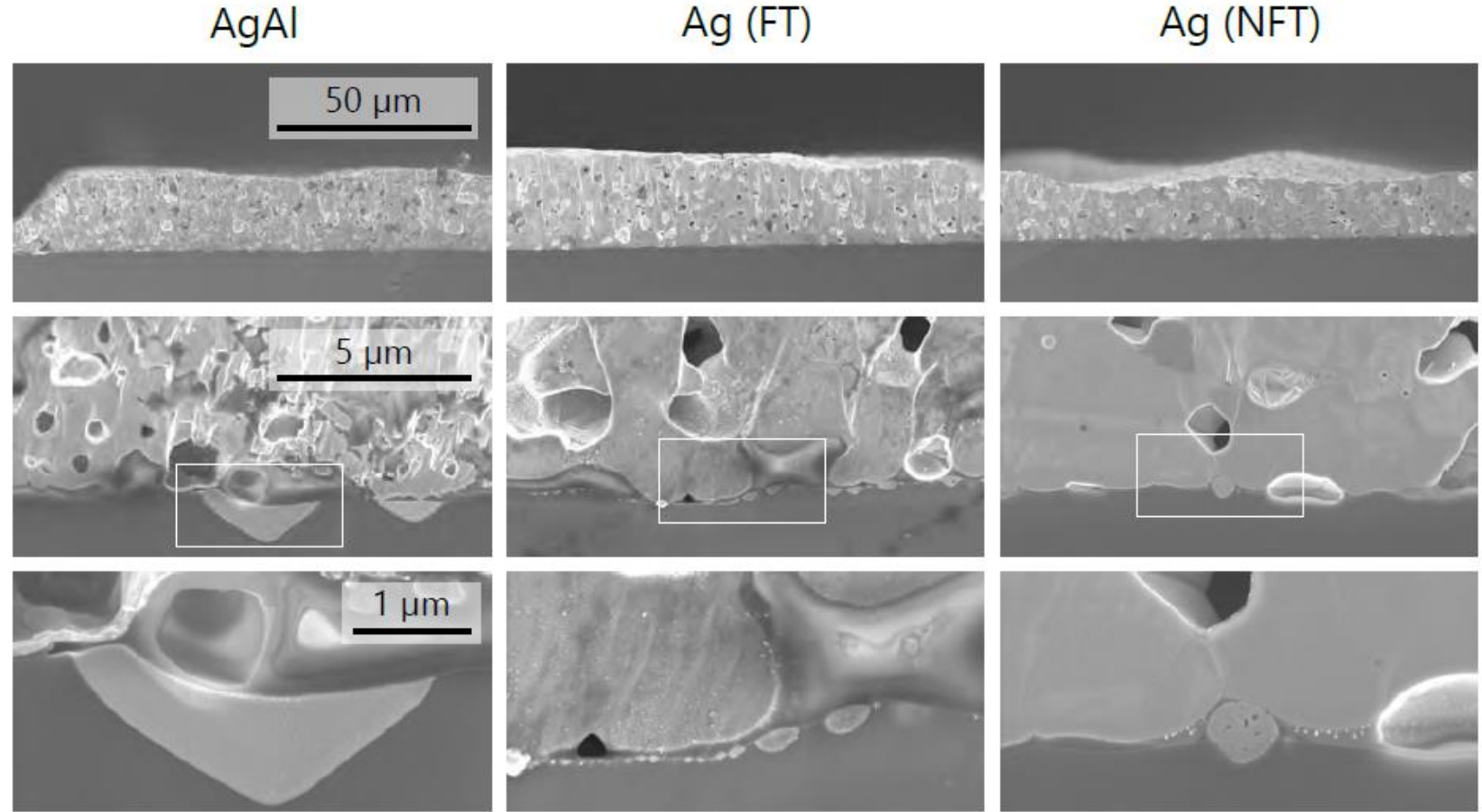


# Back-Contact Back-Junction Silicon Solar Cells

## Leanest process option

### Screen printed metallization

- Testing of Ag and AgAl pastes for  $p^{++}$  and  $n^{++}$  doping
  - Ag paste with and without “Fire-Through” properties
- Ag contacts on (planar) surfaces with  $p^{++}$  doping
  - AgAl:  $1.3 \text{ m}\Omega / \text{cm}^2$
  - Ag (FT):  $1.2 \text{ m}\Omega / \text{cm}^2$
  - Ag (NFT):  $2.6 \text{ m}\Omega / \text{cm}^2$  (w/ LCO)
- Contact resistivity on  $n^{++}$  doping much lower
- Developed layout for half cell interconnection and 24 wires



# Back-Contact Back-Junction Silicon Solar Cells

## Leanest process option

- Implementation of different process modules into baseline
  - Destruction of baseline due to PV-TEC fire (2017)

	Area (cm <sup>2</sup> )	$j_{SC}$ (mA/cm <sup>2</sup> )	$V_{OC}$ (mV)	$FF$ (%)	$\eta$ (%)	
Co-Diffusion PECVD PSG, BSG	4	40.8	664	78.0	21.1	*
Co-Diffusion PECVD PSG + printed BSG	4	40.2	659	77.7	20.6	*
Co-Diffusion POCl <sub>3</sub> + printed BSG + etch- back	4	40.2	634	74.4	19.0	
Co-Diffusion POCl <sub>3</sub> + printed BSG + etch- back	4	40.5	614	71.4	17.8	◇
All screen printed + etch-back	4	40.5	626	66.1	16.8	◇

\* Results certified by Fraunhofer ISE CalLab

◇ Process in surrogate laboratory after PV-TEC

Very precise printing  
accuracy necessary

Preparation (3 steps)

Junction Formation (4 steps)

Surface Passivation (5 steps)

Metallization (2 steps)

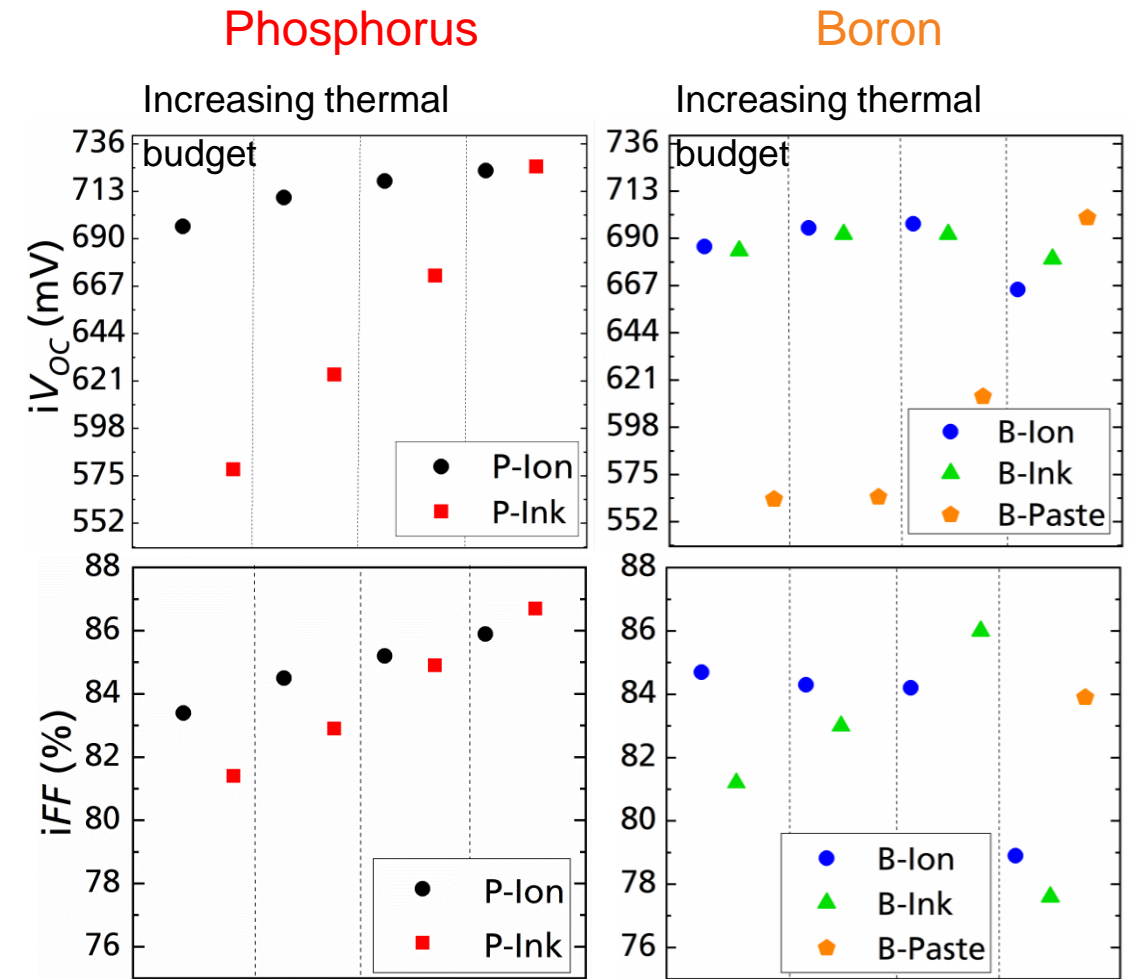
# Back-Contact Back-Junction Silicon Solar Cells

## TOPCon-IBC with printed dopant sources

- Tested printed dopants on (i) a-Si
- Annealing at different conditions
- $iV_{oc}$  of doped poly-Si can reach similar level as ion implantation

Dopant Source	$iV_{oc}$ (mV)	$iFF$ (%)
P-Ion*	732	87.3
P-Ink*	733	86.4
B-Ion	698	84.3
B-Ink	692	83.2
B-Paste	700	83.9

\*Results after RPHP





# 02

## Back-Contact Applications Integrated PV

# Wire interconnection for IBC

No bow due to super soft wires

## Super Soft Wires

- Developed manufacturing and interconnection process for “super soft wires”
- Wires are wave shaped
  - Reduced stress after soldering process
- Especially useful for back-contact solar cells
  - Demonstrated for BCBJ and MWT

3 ribbons on busbars



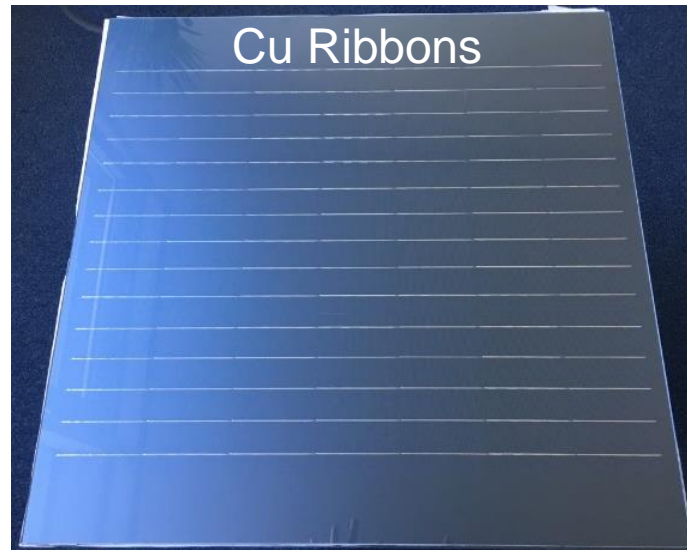
30 wave-shaped wires on fingers



# PV everywhere

## Integrated PV

- Small sized demo modules
- Different cell interconnection
- Laminates with MorphoColor®





# PV everywhere

## Integrated PV

- Supreme architectural options:  
MorphoColor® coating and low reflective PV components (*i.e.* black)
- BIPV market in Germany
  - Roofs and facade: 37 700 km<sup>2</sup>
  - Economic potential: 1400 – 4400 GWp (22 % facade)

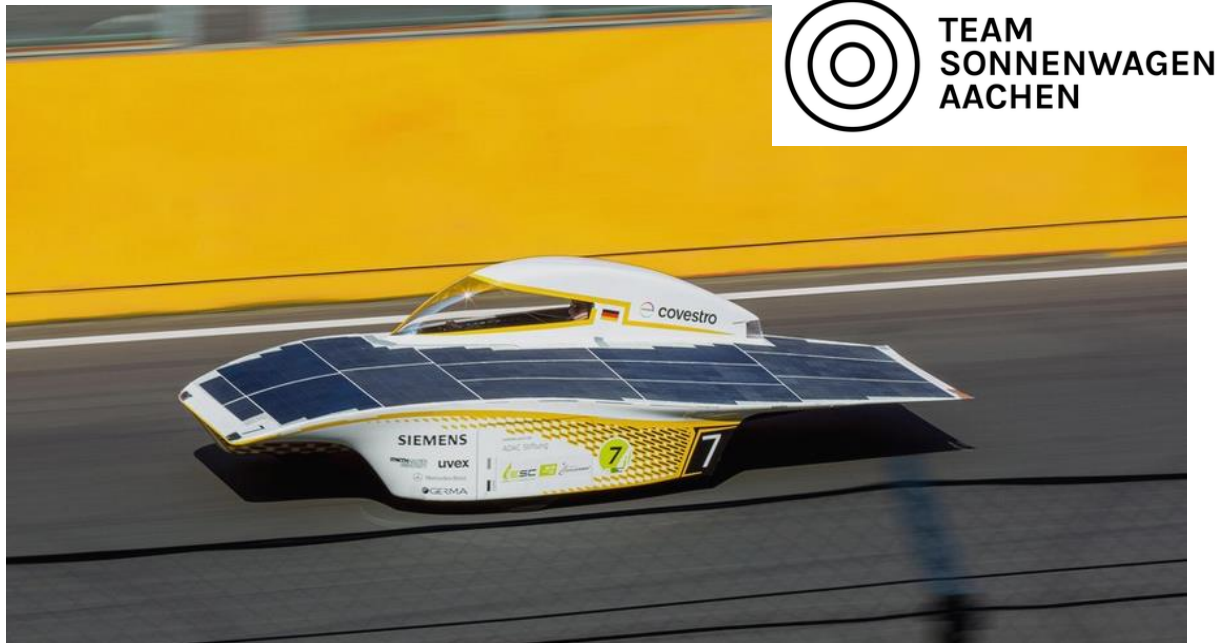


# PV everywhere

## Integrated PV

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- Solar car roofs (Solar challenge)
- 3-10 km / day for EV (today)
- Technical Potential for VIPV in Germany:
  - 25.5 GWp and more (higher integration)

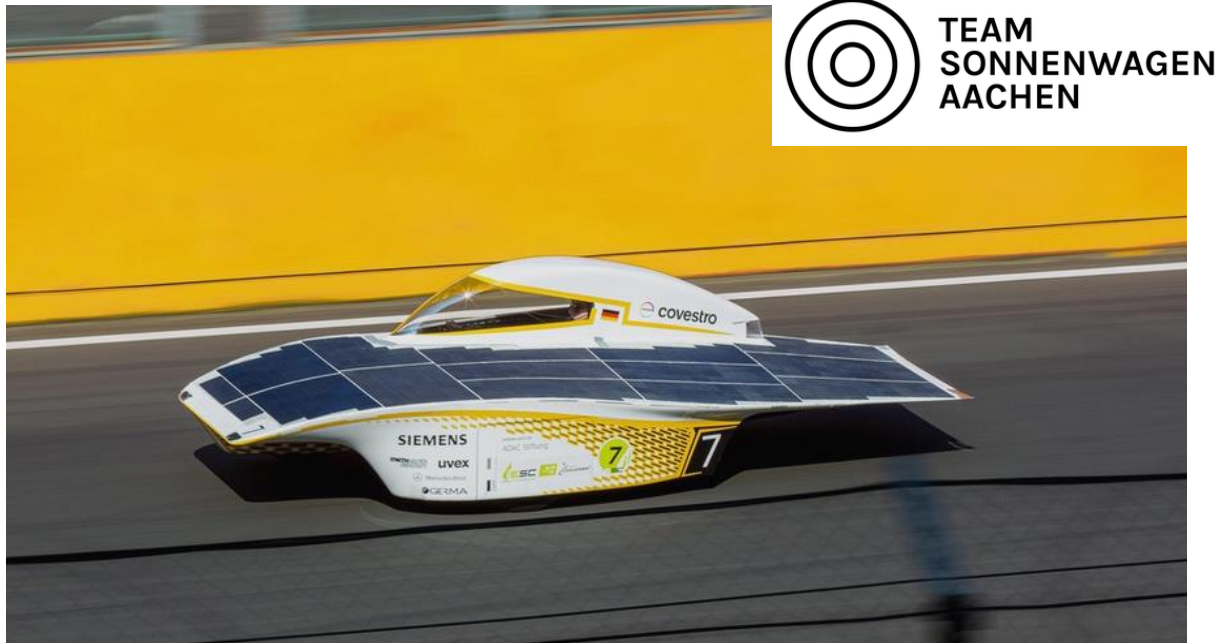


Wirth *et al.*, 36. PV-Symposium, 2021.

# PV everywhere

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Ola Källenius [in](#) • 3.+

Vorstandsvorsitzender von Mercedes-Benz

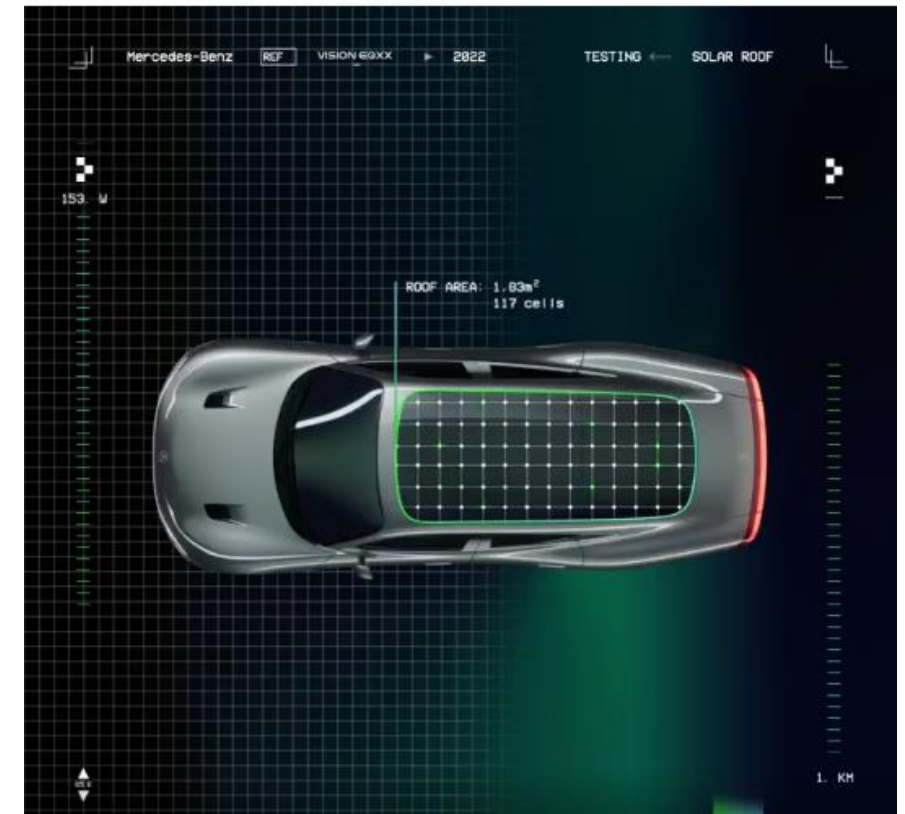
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We are currently intensifying the real-world testing of our [#VISIONEQXX](#) to see what the most efficient Mercedes ever built - with a drag coefficient of just 0.17 - can really deliver on the road.

It uses [#renewable](#) [#energy](#) from the sun to go even further: 117 individual solar cells on the roof turn the vehicle into a solar power plant in its own right, feeding the battery with up to 25 kilometres of extra range.

[Übersetzung anzeigen](#)



Wirth *et al.*, 36. PV-Symposium, 2021.



# 03

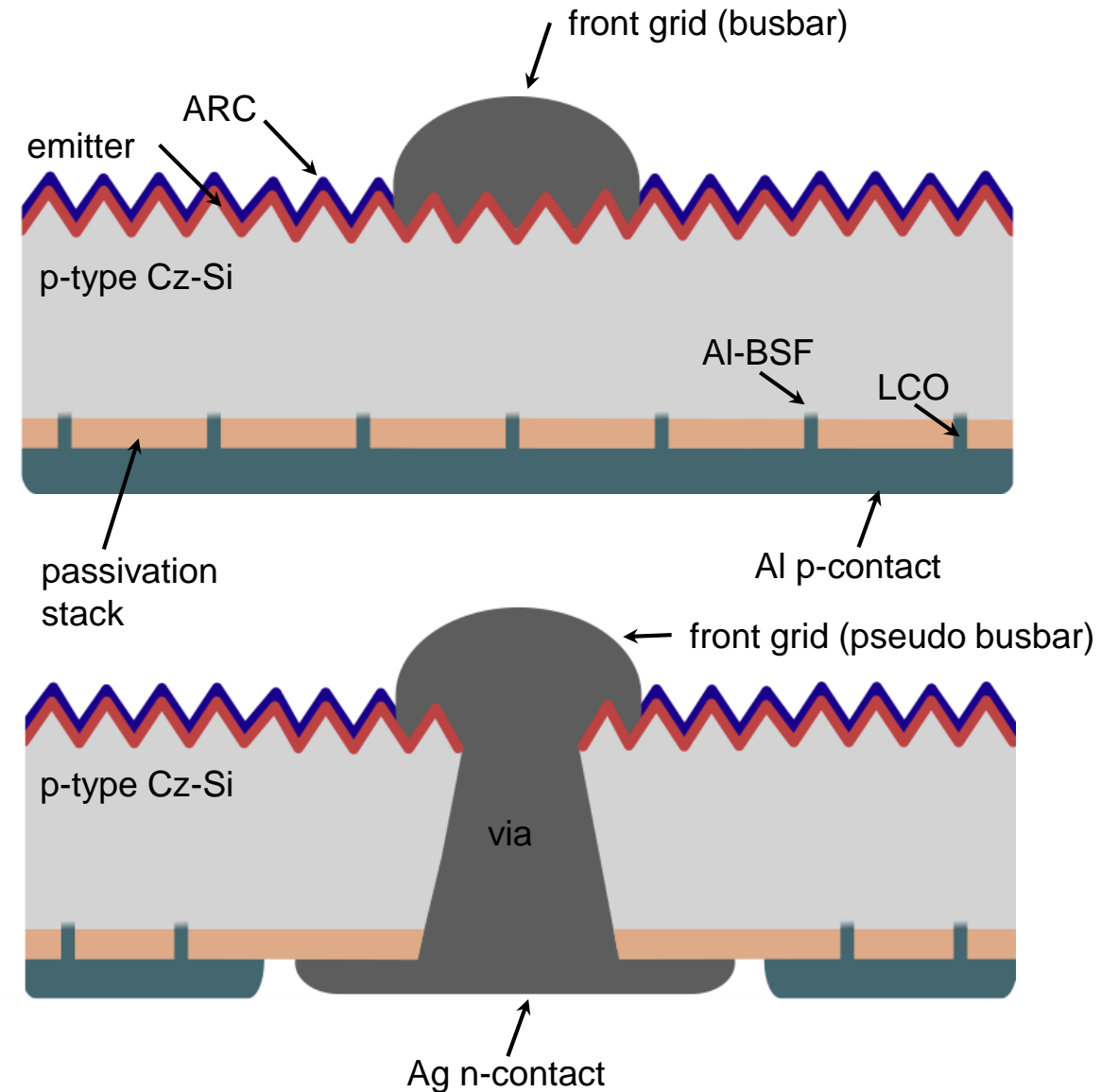
MWT solar cells for BC applications  
PERC-based BC devices

# Metal Wrap Through Solar Cells Based on PERC Front-End Processing

- Improved front side light absorption
- One sided interconnection, tighter spacing
- Fully compatible to standard PERC front-end
  - Using an industrial precursor

Area (cm <sup>2</sup> )	$j_{sc}$ (mA/cm <sup>2</sup> )	$V_{oc}$ (mV)	$FF$ (%)	$\eta$ (%)
244	40.2	674	79.2	21.4

- Layout adaptable to applications (“all-purpose MWT”)
  - Adjustments only in back-end
  - Flexible product size, wafer based processing

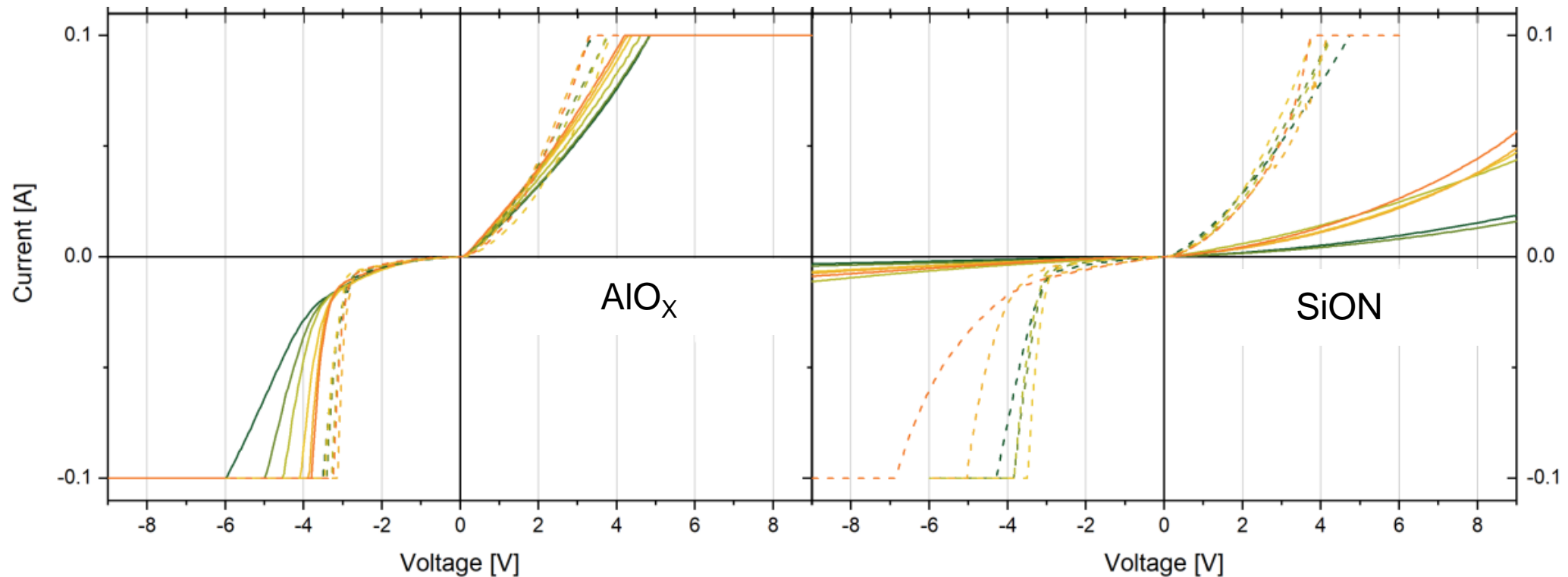
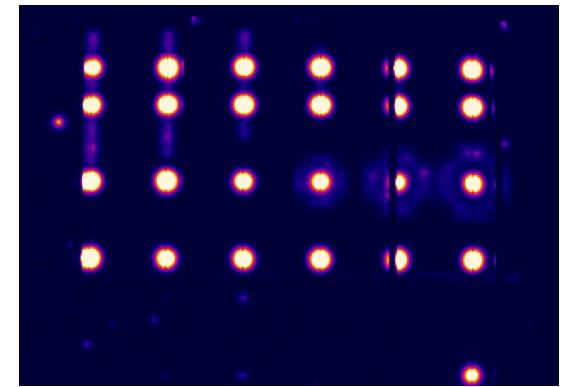


Schweigstill *et al.*, EUPVSEC, 2021.

# Metal Wrap Through Solar Cells Based on PERC Front-End Processing

- Soft breakdown in reverse bias with charged dielectric
  - Breakdown on n-contact pad

Solid line: with dielectric  
Dashed line: with dielectric removed



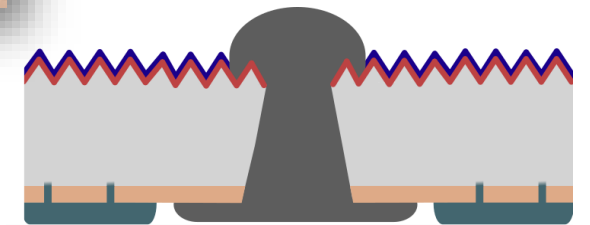
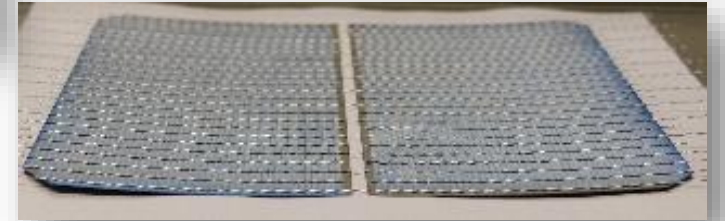
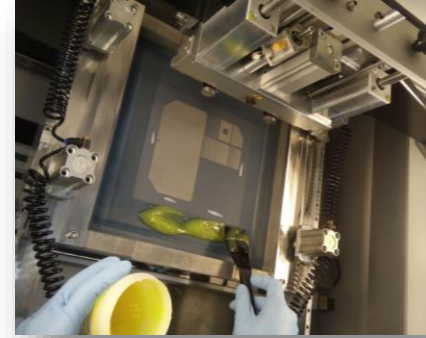
Schweigstill *et al.*, EUPVSEC, 2021.



# Back-contact solar cells at Fraunhofer ISE

## Summary

- Demonstrated a very lean process flow: „All screen-printed BCBJ“
  - Challenges remain in alignment accuracy
  - Optimization of processes to improve performance
  - Simulated potential of up to 23 % (without pass. contacts)
- Super soft wires for one-sided interconnection
  - Avoiding bow after soldering
- Back-contact a supreme choice for Integrated PV
  - Increased output on smaller areas (cell performance, spacing)
  - Very appealing aesthetics, combination with color coatings
- MWT process compatible to state-of-the-art PERC
  - Keep some advantages of BCBJ
  - Very lean process flow
  - Easily adjustable for different applications in back-end





# Contact

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